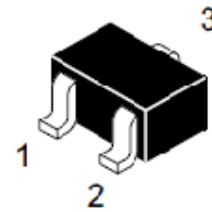


## WPM1488

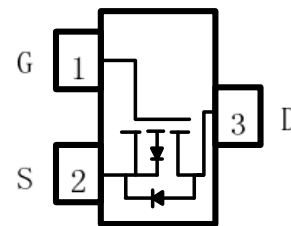
Single P-Channel, -12V, -1.4A, Power MOSFET

www.sh-willsemi.com

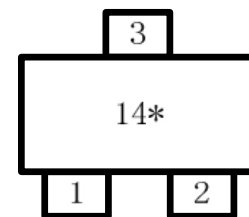
V <sub>DS</sub> (V)	Typical R <sub>ds(on)</sub> (Ω)	I <sub>D</sub> (A)
-12	0.080@ V <sub>GS</sub> = - 4.5V	-1.2
	0.086@ V <sub>GS</sub> = - 3.6V	-1.0
	0.105@ V <sub>GS</sub> = - 2.5V	-1.0



SOT-323



Pin configuration (Top view)



14 = Specific Device Code

\* = Date Code

### Marking

### Order information

Device	Package	Shipping
WPM1488-3/TR	SOT-323	3000/Reel&Tape

### Descriptions

The WPM1488 is P-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent R<sub>DS (ON)</sub> with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WPM1488 is Pb-free.

### Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance for higher DC current
- Extremely Low Threshold Voltage
- Small package SOT-323

### Applications

- Driver for Relay, Solenoid, Motor, LED etc.
- DC-DC converter circuit
- Power Switch
- Load Switch
- Charging

**Absolute Maximum ratings**

Parameter		Symbol	10 S	Steady State	Unit
Drain-Source Voltage		$V_{DS}$	-12		V
Gate-Source Voltage		$V_{GS}$	$\pm 8$		
Continuous Drain Current <sup>a d</sup>	$T_A=25^\circ\text{C}$	$I_D$	-1.5	-1.4	A
	$T_A=70^\circ\text{C}$		-1.2	-1.1	
Maximum Power Dissipation <sup>a d</sup>	$T_A=25^\circ\text{C}$	$P_D$	0.44	0.38	W
	$T_A=70^\circ\text{C}$		0.28	0.25	
Continuous Drain Current <sup>b d</sup>	$T_A=25^\circ\text{C}$	$I_D$	-1.4	-1.3	A
	$T_A=70^\circ\text{C}$		-1.1	-1.1	
Maximum Power Dissipation <sup>b d</sup>	$T_A=25^\circ\text{C}$	$P_D$	0.39	0.34	W
	$T_A=70^\circ\text{C}$		0.25	0.22	
Pulsed Drain Current <sup>c</sup>		$I_{DM}$	-10		A
Operating Junction Temperature		$T_J$	-55 to 150		$^\circ\text{C}$
Lead Temperature		$T_L$	260		$^\circ\text{C}$
Storage Temperature Range		$T_{stg}$	-55 to 150		$^\circ\text{C}$

**Thermal resistance ratings**

Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance <sup>a</sup>	t 10 s	$R_{JA}$	284	335	$^\circ\text{C/W}$
	Steady State		321	385	
Junction-to-Ambient Thermal Resistance <sup>b</sup>	t 10 s	$R_{JA}$	315	338	
	Steady State		358	415	
Junction-to-Case Thermal Resistance	Steady State	$R_{JC}$	110	165	

a Surface mounted on FR-4 Board using 1 square inch pad size, 1oz copper

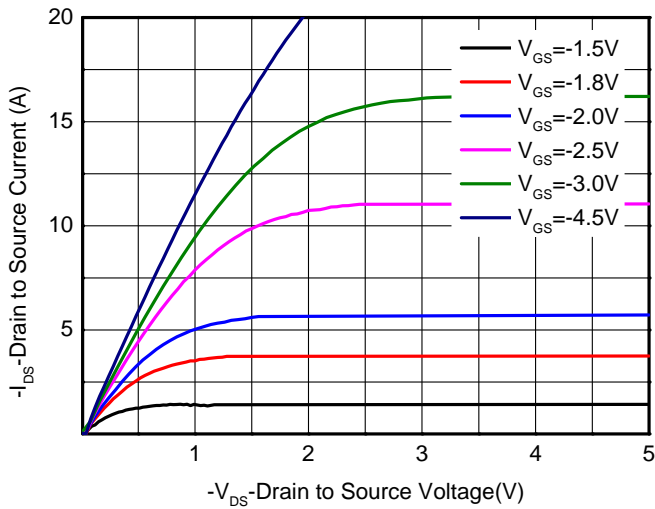
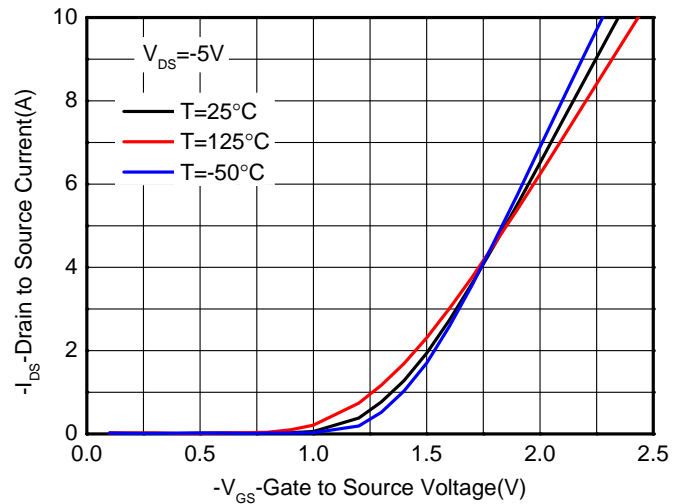
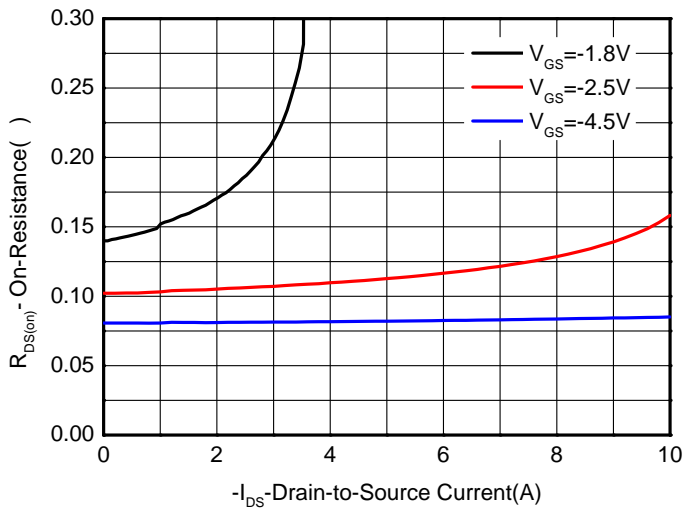
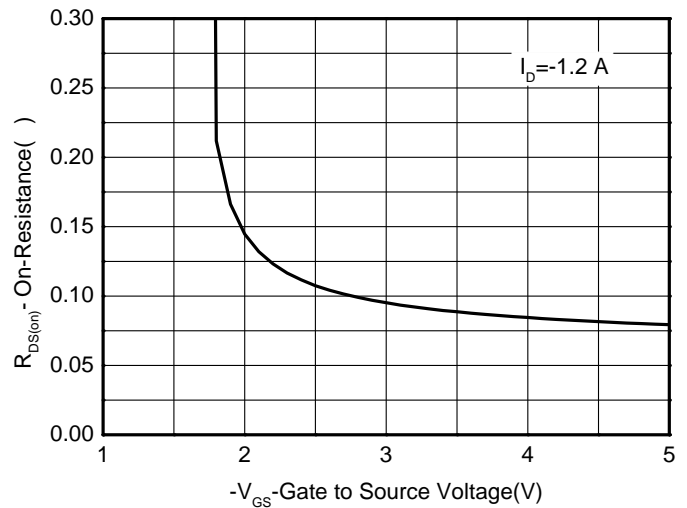
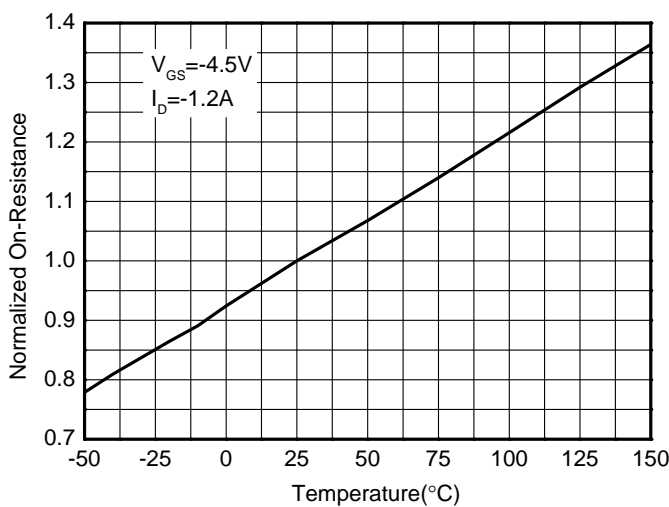
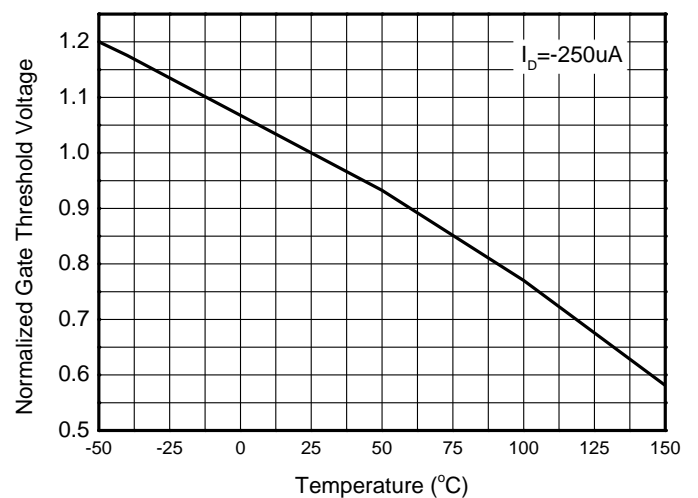
b Surface mounted on FR-4 board using minimum pad size, 1oz copper

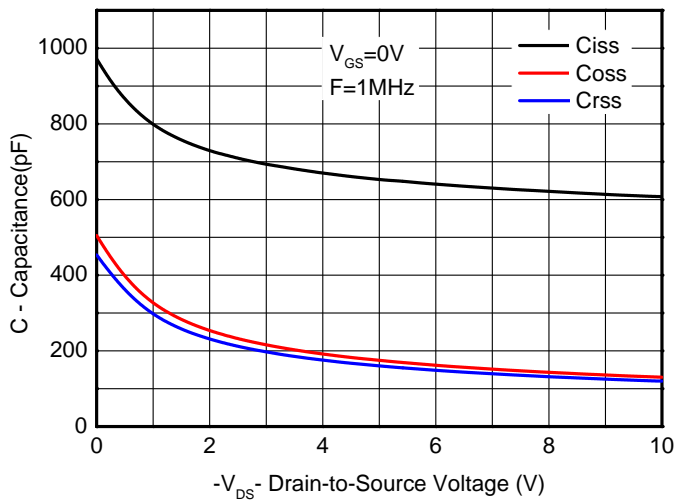
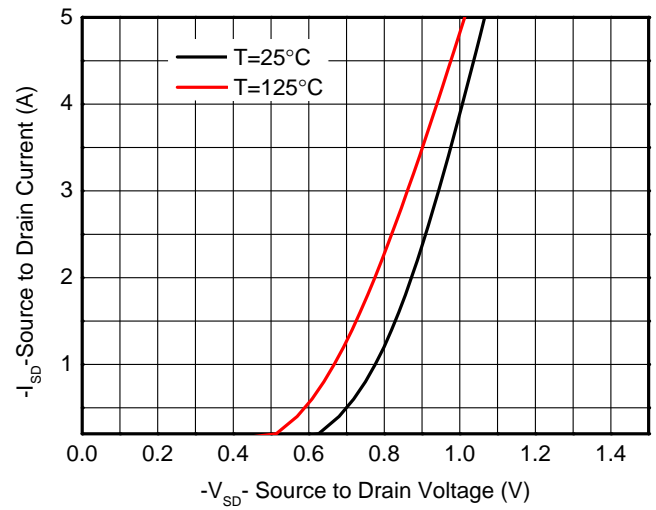
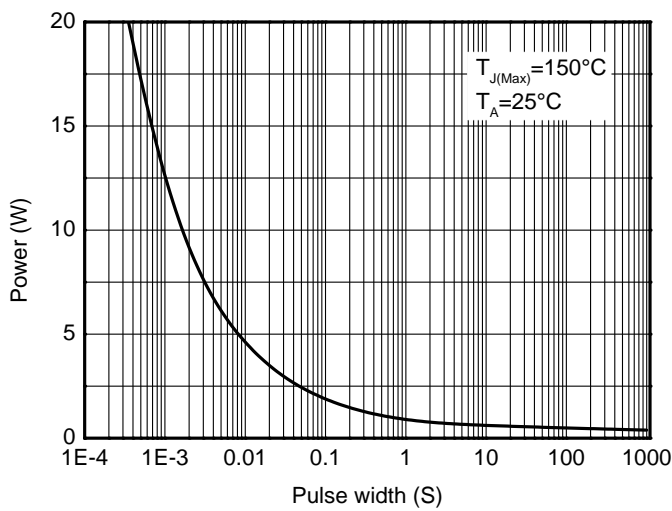
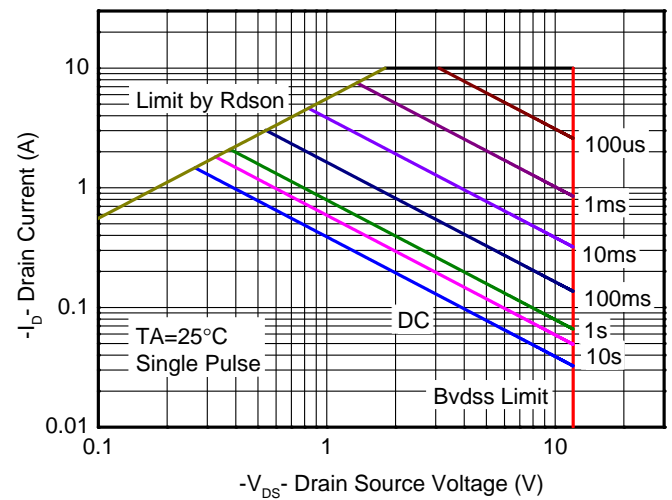
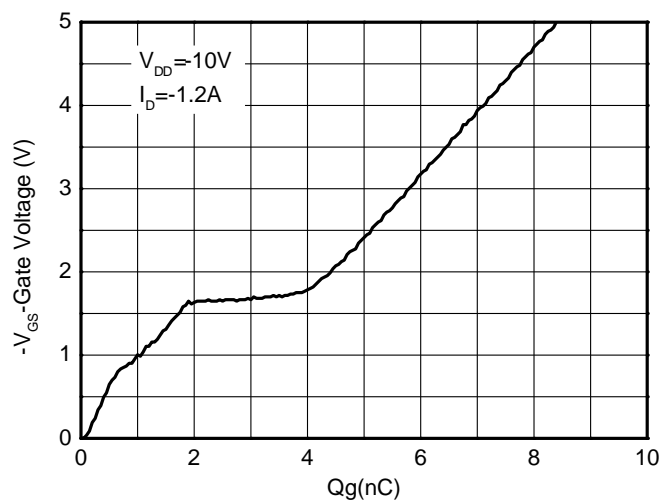
c Pulse width<380 $\mu\text{s}$ , Duty Cycle<2%

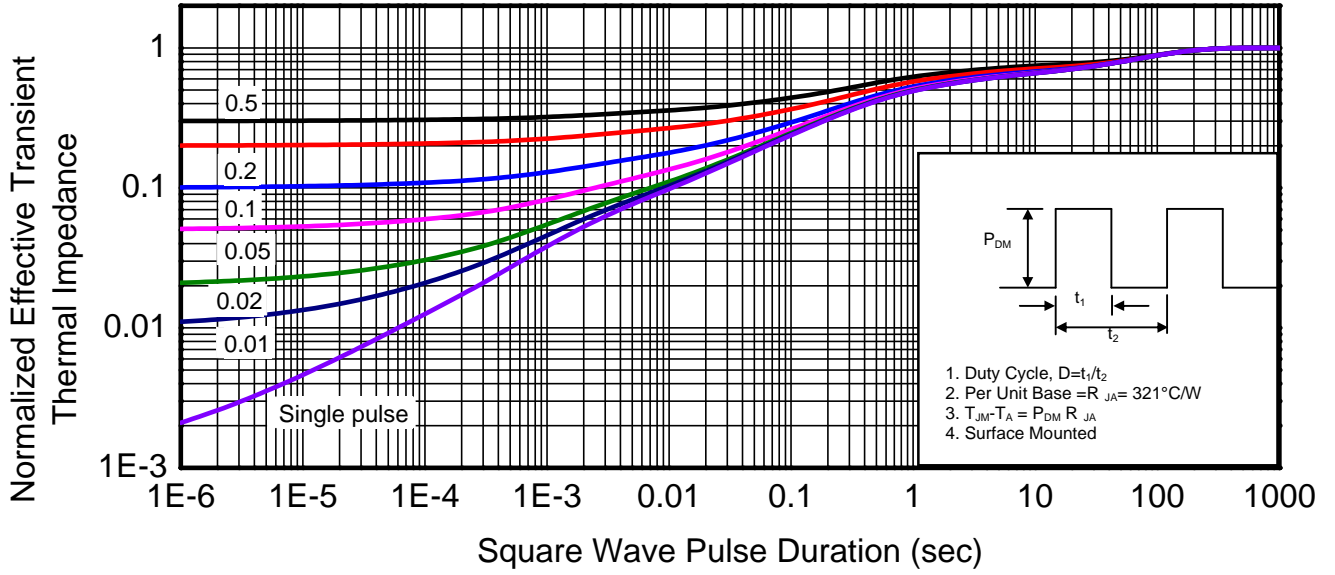
d Maximum junction temperature  $T_J=150^\circ\text{C}$ .

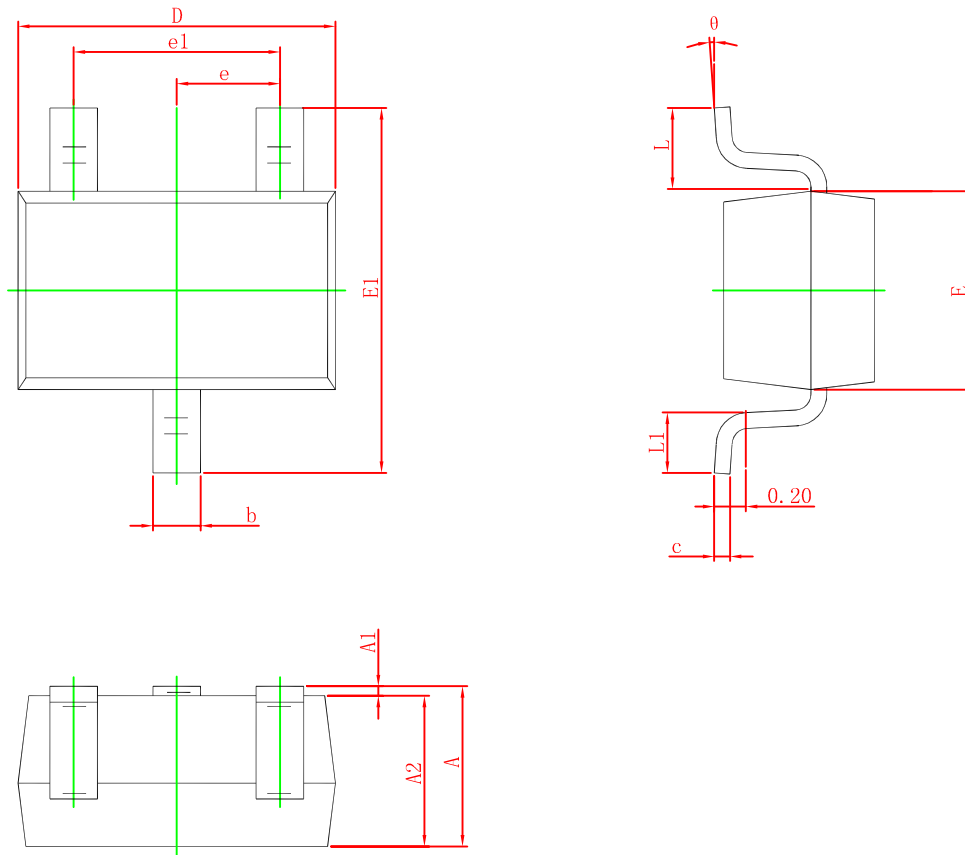
**Electronics Characteristics (Ta=25°C, unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0\text{ V}, I_D = -250\mu\text{A}$	-12			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -10\text{V}, V_{GS} = 0\text{V}$			-1	$\mu\text{A}$
Gate-to-source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 8\text{V}$			$\pm 1$	$\mu\text{A}$
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = -250\mu\text{A}$	-0.45	-0.65	-0.85	V
Drain-to-source On-resistance <sup>b, c</sup>	$R_{DS(on)}$	$V_{GS} = -4.5\text{V}, I_D = -1.2\text{A}$		80	120	m $\Omega$
		$V_{GS} = -3.6\text{V}, I_D = -1.0\text{A}$		86	140	
		$V_{GS} = -2.5\text{V}, I_D = -1.0\text{A}$		105	160	
Forward Transconductance	$g_{FS}$	$V_{DS} = -5\text{V}, I_D = -1.2\text{A}$		9		S
<b>CAPACITANCES, CHARGES</b>						
Input Capacitance	$C_{ISS}$	$V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz},$ $V_{DD} = -10\text{ V}$		607		pF
Output Capacitance	$C_{OSS}$			130		
Reverse Transfer Capacitance	$C_{RSS}$			120		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = -4.5\text{ V},$ $V_{DD} = -10\text{ V},$ $I_D = -1.2\text{A}$		7.85		nC
Threshold Gate Charge	$Q_{G(TH)}$			0.85		
Gate-to-Source Charge	$Q_{GS}$			1.9		
Gate-to-Drain Charge	$Q_{GD}$			2.1		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = -4.5\text{ V},$ $V_{DD} = -10\text{V},$ $I_D = -1.2\text{A},$ $R_G = 6\ \Omega$		30		ns
Rise Time	$t_r$			32		
Turn-Off Delay Time	$t_{d(off)}$			62		
Fall Time	$t_f$			18		
<b>BODY DIODE CHARACTERISTICS</b>						
Forward Voltage	$V_{SD}$	$V_{GS} = 0\text{ V}, I_S = -1.0\text{A}$		-0.8	-1.5	V

**Typical Characteristics (Ta=25°C, unless otherwise noted)**

**Output characteristics**

**Transfer characteristics**

**On-Resistance vs. Drain current**

**On-Resistance vs. Gate-to-Source voltage**

**On-Resistance vs. Junction temperature**

**Threshold voltage vs. Temperature**


**Capacitance**

**Body diode forward voltage**

**Single pulse power**

**Safe operating power**

**Gate charge Characteristics**

**Transient thermal response (Junction-to-Ambient)**


**Package outline dimensions**
**SOT-323**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP.		0.026 TYP.	
e1	1.200	1.400	0.047	0.055
L	0.525 REF.		0.021 REF.	
L1	0.260	0.460	0.010	0.018
$\theta$	0°	8°	0°	8°